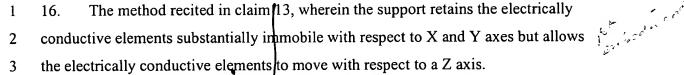
## CLAIMS

## What is claimed is:

- 1 1. A method comprising:
- 2 providing a connector comprising a plurality of electrically conductive
- 3 elements in a thin, flexible, electrically insulating support; and
- 4 coupling lands on an integrated circuit (IC) to corresponding lands on a
- 5 substrate with the electrically conductive elements.
- 1 2. The method recited in claim 1, wherein the electrically conductive elements
- 2 comprise a compressible material.
- 1 3. The method recited a claim 2, wherein the compressible material comprises
- 2 a wire wad.
- 1 4. The method recited in claim 1, wherein the support comprises a hole for
- 2 each electrically conductive element.
- 1 5. The method recited in claim 1, wherein the support comprises a flexible
- 2 sheet.
- 1 6. The method recited in claim 1, wherein the electrically conductive elements
- 2 comprise crystals.
- 1 7. The method recited in claim 6, wherein the crystals comprise a coating of
- 2 electrically conductive material.
- 1 8. The method recited in claim 1 and further comprising:
- 2 securing the IC, support, and substrate in a package.

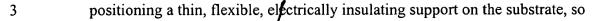
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- 1 9. The method recited in claim 8 wherein securing is performed by a package 2 lid.
- 1 10. The method recited in claim 8, wherein securing comprises physically
- 2 compressing the IC, support, and substrate.
- 1 11. The method recited in claim 1 and further comprising:
- 2 providing an additional connector comprising a plurality of electrically
- 3 conductive elements in a thin, flexible, electrically insulating support; and
- 4 coupling lands on an IC package to corresponding lands on an additional substrate
- 5 with the electrically conductive elements of the additional connector.
- 1 12. The method recited in claim N, wherein the additional substrate comprises
- 2 a printed circuit board.
- 1 13. A method comprising:
- 2 providing a connector comprising a plurality of electrically conductive
- 3 elements in a thin, flexible, electrically insulating support; and
- 4 coupling lands on an integrated circuit (IC) package to corresponding lands on a
- 5 substrate with the electrically conductive elements.
- 1 14. The method recited in claim 13, wherein the electrically conductive elements
- 2 comprise a compressible material.
- 1 15. The method recited in claim 14, wherein the compressible material
- 2 comprises a wire wad.

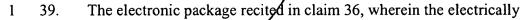


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- 3
- The method recited in claim 13, wherein the support comprises a hole for 1 17.
- each electrically conductive element. 2
- The method recited in claim 13, wherein the support comprises a flexible 18. 1
- 2 sheet.
- The method recited in claim 18, wherein the sheet comprises a plastic. 1 19.
- The method recited in claim 18, wherein the electrically conductive elements 1 20.
- 2 comprise pins in the sheet.
- The method recited in claim 13, wherein the electrically conductive elements 1 21.
- comprise regular geometric objects. 2
- The method recited in claim 13, wherein the electrically conductive elements 22. 1
- 2 comprise irregular geometric objects.
- The method recited in claim 13, wherein the electrically conductive elements 1 23.
- comprise material from the group comprising aluminum, antimony, beryllium, 2
- 3 bismuth, cadmium, carbon, chromium, copper, gold, iron, lead, magnesium,
- manganese, molybdenum, nickel, palladium, platinum, silicon, silver, tin, titanium, 4
- tungsten, zinc, metal silicide, doped polysilicon, and plastic. 5
- The method recited in claim 13, wherein the electrically conductive elements 1 24.
- comprise crystals. 2

- 1 25. The method recited in claim 24, wherein the crystals comprise a coating of
- 2 electrically conductive material.
- 1 26. The method recited in claim 13 and further comprising:
- 2 securing the IC package, support, and substrate in a package.
- 1 27. The method recited in claim 26, wherein securing is performed by a package
- 2 lid.
- 1 28. The method recited in claim 26, wherein securing comprises physically
- 2 compressing the IC package, support, and substrate.
- 1 29. A solderless method of mounting an integrated circuit (IC) on a substrate,
- 2 the method comprising:
- positioning a thin, flexible, electrically insulating support on the substrate, so
- 4 that a plurality of electrically conductive elements on the support are aligned with
- 5 respect to a corresponding plurality of lands on the substrate; and
- 6 positioning the IC on the support, so that a plurality of lands on the IC are aligned
- 7 with respect to a corresponding plurality of electrically conductive elements on the
- 8 support.
- 1 30. The method recited in claim 29, wherein the operations are performed in the
- 2 order recited.
- 1 31. The method recited in claim 29 and further comprising:
- 2 compressing the IC, support, and substrate together to maintain electrical contact
- between the lands on the C and the lands on the substrate.
- 1 32. A solderless method of mounting an integrated circuit (IC) package on a
- 2 substrate, the method comprising:



- 4 that a plurality of electrically conductive elements on the support are aligned with
- 5 respect to a corresponding plurality of lands on the substrate; and
- 6 positioning the IC package on the support, so that a plurality of lands on the IC
- 7 package are aligned with respect to a corresponding plurality of electrically
- 8 conductive elements on the support.
- 1 33. The method recited in claim 32, wherein the operations are performed in the
- 2 order recited.
- 1 34. The method recited in claim 32 and further comprising:
- 2 compressing the IC package, support, and substrate together to maintain electrical
- 3 contact between the lands on the IC package and the lands on the substrate.
  - An electronic package comprising:
    - a die;
    - a substrate; and
- 4 a compressible connector to couple the die to the substrate.
- 1 36. The electronic package recited in claim 35, wherein the connector comprises
- 2 a plurality of electrically conductive elements to couple lands on the die to
- 3 corresponding lands on the substrate.
- 1 37. The electronic package recited in claim 36 and further comprising:
- 2 a compression element to maintain electrical contact between the lands on the die
- 3 and the lands on the substrate.
- 1 38. The electronic package recited in claim 37, wherein the compression
- 2 element is a lid comprising a member in contact with the die and a support coupled
- 3 to the substrate.



- 2 conductive elements comprise a compressible material.
- 1 40. The electronic package recited in Elaim 35, wherein the connector
- 2 comprises:
- a flexible support formed of electrically insulating material; and
- 4 a plurality of elements formed of extrically conductive material.
- 1 41. The electronic package recited in claim 40, wherein the support is formed of
- 2 plastic, and the plurality of elements are from the group consisting of wire wads,
- 3 pins, blobs, lumps, particles, and crystals.
  - 42. The electronic package recited in claim 41, wherein the elements comprise a coating of electrically conductive material.
  - 43. The electronic package recited in claim 40, wherein the plurality of elements
- 2 comprise material from the group consisting of aluminum, antimony, beryllium,
- 3 bismuth, cadmium, carbon, chromium, copper, gold, indium, iron, lead, magnesium,
- 4 manganese, molybdenum, nickel, palladium, platinum, silicon, silver, tin, titanium,
- 5 tungsten, zinc, metal silicide, doped polysilicon, and plastic.
- 1 44. An electronic package comprising:
- 2 an integrated circuit ( $\mathbf{I}(t)$ ) package;
- 3 a substrate; and
- a compressible connector to couple the IC package to the substrate.
- 1 45. The electronic package recited in claim 44, wherein the connector comprises
- 2 a plurality of electrically/conductive elements to couple lands on the IC package to
- 3 corresponding lands on the substrate.

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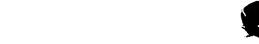
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- 2 a compression element to maintain electrical contact between the lands on the IC
- 3 package and the lands on the substrate.
- 1 47. The electronic package recited in claim 46, wherein the compression
- 2 element is a lid comprising a member in contact with the IC package and a support
- 3 coupled to the substrate.
- 1 48. The electronic package recited in claim 45, wherein the electrically
- 2 conductive elements comprise a compressible material.
- 1 49. The electronic package recited in claim 44, wherein the connector
- 2 comprises:
- a flexible support formed of electrically insulating material; and
- 4 a plurality of elements formed of electrically conductive material.
- 1 50. The electronic package recited in claim 49, wherein the support is formed of
- 2 plastic, and the plurality of elements are from the group consisting of wire wads,
- pins, blobs, lumps, particles, and crystals.
  - 51. The electronic package recited in claim 50, wherein the elements comprise a coating of electrically conductive material.
- 52. The electronic package recited in claim 49, wherein the plurality of elements
- 2 comprise material from the group consisting of aluminum, antimony, beryllium,
- 3 bismuth, cadmium, carbon, chromium, copper, gold, indium, iron, lead, magnesium,
- 4 manganese, molybdenum, nickel, palladium, platinum, silicon, silver, tin, titanium,
- 5 tungsten, zinc, metal silicide, doped polysilicon, and plastic.

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- 1 53. An electronic system comprising least one electronic assembly comprising:
- 2 an integrated circuit (IC) package;
- 3 a substrate; and
- a compressible connector to couple the IC package to the substrate.
- 1 54. The electronic system recited in claim 53, wherein the connector comprises a
- 2 plurality of electrically conductive elements to couple lands on the IC package to
- 3 corresponding lands on the substrate.
- 1 55. The electronic system recited in claim 54, wherein the at least one electronic
- 2 assembly further comprises a compression element to maintain electrical contact
- 3 between the lands on the IC package and the lands on the substrate.
- 1 56. A data processing system comprising:
- a bus coupling components in the data processing system;
- a display coupled to the bus;
- 4 external memory coupled to the bus; and
- a processor coupled to the bus and including at least one electronic assembly
- 6 comprising:
- 7 an integrated circuit (IQ) package;
- 8 a substrate; and
- 9 a compressible connector to couple the IC package to the substrate.
- 1 57. The data processing system recited in claim 56, wherein the connector
- 2 comprises a plurality of electrically conductive elements to couple lands on the IC
- 3 package to corresponding ands on the substrate.
- 1 58. The data processing system recited in claim 57, wherein the at least one
- 2 electronic assembly further comprises a compression element to maintain electrical
- 3 contact between the lands on the IC package and the lands on the substrate.

